

Maximum Ratings (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P_PP	84	W	8/20µs, per Figure 2
Peak Pulse Current	I _{PP}	6	Α	8/20µs, per Figure 2
ESD Protection – Contact Discharge	V _{ESD_Contact}	±30	kV	IEC 61000-4-2 Standard
ESD Protection – Air Discharge	V_{ESD_Air}	±30	kV	IEC 61000-4-2 Standard

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 6)	P_{D}	275	mW
Thermal Resistance, Junction to Ambient (Note 6)	$R_{ heta JA}$	454	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Conditions
Reverse Standoff Voltage	V_{RWM}	-	-	5	V	-
Channel Leakage Current (Note 7)	I _{RM}	-	10	100	nA	V _{RWM} = 5V
Clamping Voltage, Positive Transients	VcL		7.0 8.7 10.5 11.5	9.0 10.7 12.0 14.0	V	$I_{PP} = 1A$, $tp = 8/20\mu S$ $I_{PP} = 3A$, $tp = 8/20\mu S$ $I_{PP} = 5A$, $tp = 8/20\mu S$ $I_{PP} = 6A$, $tp = 8/20\mu S$
Breakdown Voltage	V_{BR}	6	7	8	V	$I_R = 1mA$
Differential Resistance	R_{DIF}	-	0.2	-	Ω	$I_R = 1A$, $tp = 8/20 \mu S$
Channel Input Capacitance	C _{IN}	-	15	20	pF	$V_R = 0V$, $f = 1MHz$

Notes:

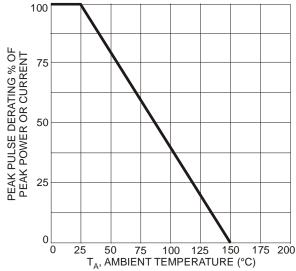
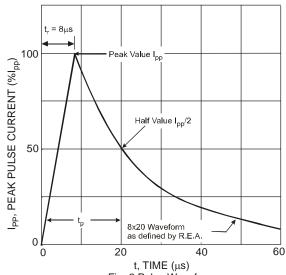


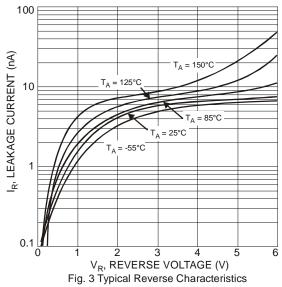
Fig. 1 Power Dissipation vs. Ambient Temperature

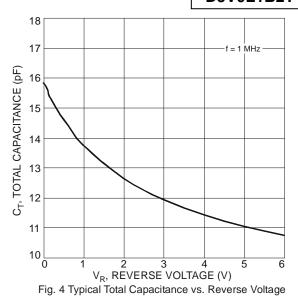


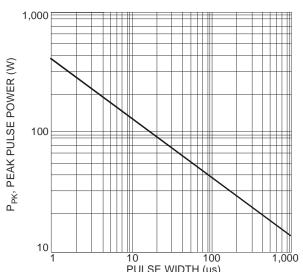
^{6.} Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at http://www.diodes.com.

7. Short duration pulse test used to minimize self-heating effect.





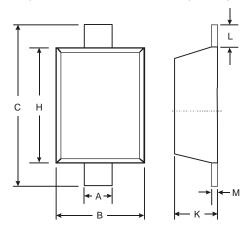




 $\begin{array}{ccc} & 10 & 100 & 1 \\ & \text{PULSE WIDTH (}\mu\text{s}) & \\ \text{Fig. 5 Pulse Rating Curve vs. Pulse Width} & \\ & \text{Power is defined as P}_{\text{PK}} = \text{V}_{\text{C}} \times \text{I}_{\text{PP}} & \\ \end{array}$

Package Outline Dimensions

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

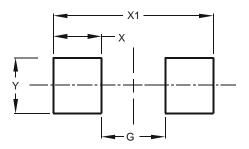


SOD523			
Dim	Min	Max	
Α	0.25	0.35	
В	0.70	0.90	
С	1.50	1.70	
Н	1.10	1.30	
K	0.55	0.65	
L	0.10	0.30	
M	0.10	0.12	
All Dimensions in mm			



Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
G	0.80
Х	0.60
X1	2.00
Υ	0.70

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